- ✧ Protects one I/O or power line
- ✧

| Reflow Condition | | Pb-Free assembly (see figure at right) |
|---|---|---|
| Pre Heat | -Temperature Min ($T_{s(min)}$) | +150 |
| | -Temperature Max($T_{s(max)}$) | +200 |
| | -Time (Min to Max) (ts) | 60-180 secs. |
| Average ramp up rate (Liquidus Temp ($T_L$)to peak) | | 3 /sec. Max |
| $T_{s(max)}$ to $T_L$ - Ramp-up Rate | | 3 /sec. Max |
| Reflow | -Temperature($T_L$)(Liquidus) | +217 |
| | -Temperature($t_L$) | 60-150 secs. |
| Peak Temp ($T_p$) | | +260(+0/-5) |
| Time within 5 of actual Peak Temp ($t_p$) | | 20-40secs. |
| Ramp-down Rate | | 6 /sec. Max |
| Time 25 to Peak Temp ($T_P$) | | 8 min. Max |
| Do not exceed | | +260 |

**for ESD Protection**